

## KEY FEATURES

### PRODUCT FEATURES:

- ☒ Electrically insulating
- ☒ Non-silicone, non-reactive, non-curing system with no resin-filler separation
- ☒ High thermal stability, with continuous operation up to 150°C
- ☒ High thermal conductivity
- ☒ Easy pick and place application (naturally sticky) without residue/mess
- ☒ Highly compressible to minimize contact resistance without high force and component stress



## TECHNICAL SPECIFICATIONS

Test	Description	Min	Max
Thermal Conductivity	ASTM D5470	> 15 W/m*K	
Thermal Impedance vs Pressure *	ASTM D5470	0.99 °C-cm <sup>2</sup> /W (0.153°C-inch <sup>2</sup> /W) @10 psi 0.59 °C-cm <sup>2</sup> /W (0.092 °C-inch <sup>2</sup> /W) @30 psi	
Continuous Use Temperature	Thermexit In-House Method	-40°C	150°C
Storage Temperature/Shelf Life	Thermexit In-House Method	12 months when stored at 10-40°C	
Total Mass Loss/TGA	Thermal stability (TGA)	<0.2% @150°C	
Hardness	ASTM D2240	77 Shore 00	87 Shore 00
Outgassing CVMC (Collectible Volatile Condensable Materials)	ASTM E595	0.07 Wt. %	
Outgassing TML (Total Mass Loss)	ASTM E595	0.20 Wt.%	
Compression-Deflection **	ASTM D5470/ASTM C165	17% at 30psi	
Electrical Resistance	ASTM D257, volume resistivity	1x10 <sup>14</sup> Ohm-cm	
Dielectric Constant /Dielectric Loss	ASTM D150/Thermexit In-House Method	4.73* / 0.009 @ 1MHz	
Dielectric Strength (Voltage Breakdown)	ASTM D149	200 (7875) Vac/mil (Vac/mm)	
Length***	Major axis of the pad footprint, +/-10%	5mm	50mm
Width***	Minor axis of the pad footprint, +/-10%	5mm	50mm
Thickness***	Thickness of the pad, +/-10%	0.5mm	5mm
Density (Specific Gravity)	ASTM D0792	1.71 g/mL	
Standard Color	Thermexit In-House Method	White	

\*0.5mm thickness: additional data available, \*\*2mm thickness; additional data available

\*\*\*Standard length/width sizes are 20mm x 20mm or 50mm x 50mm. Refer to Product Variation Catalog for complete sizing list.

### Disclaimer

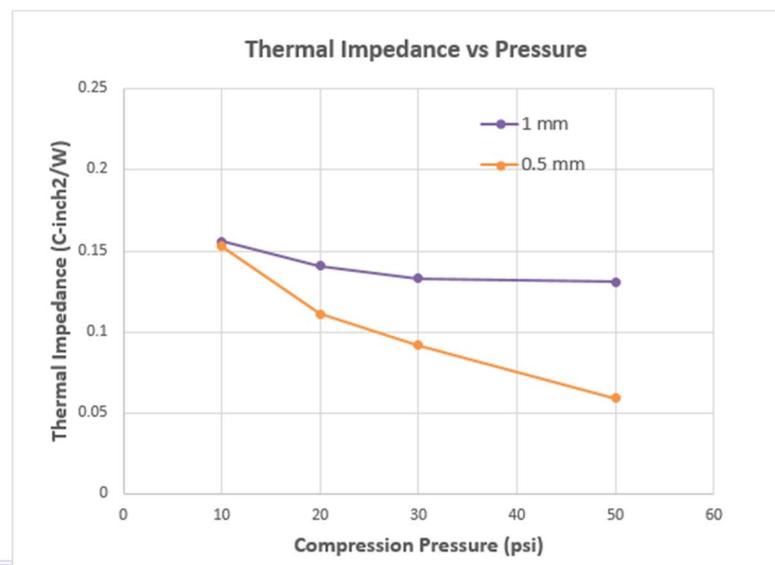
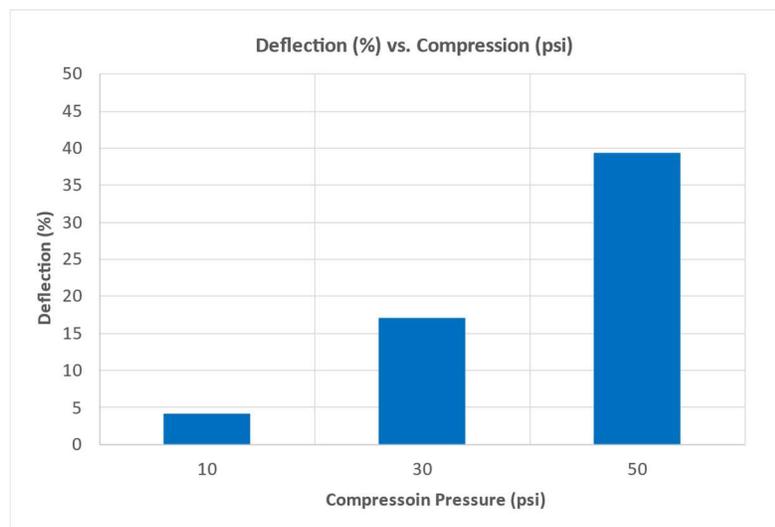
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**Thermexit™**

## TYPICAL APPLICATIONS

### MARKET APPLICATIONS

- ☰ Consumer electronics
- ☰ Power supplies
- ☰ Automotive electronics
- ☰ LED, LCD and optical displays
- ☰ Motor controls
- ☰ High power density semiconductors
- ☰ Batteries or energy storage devices



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Rev Number	27
Last Updated	06/23/2021

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### PRODUCT FEATURES:

- ≡ Non-silicone, non-reactive, non-curing system with no resin-filler separation
- ≡ High thermal stability, with continuous operation up to 150°C
- ≡ High thermal conductivity (40W/mK)
- ≡ Easy pick and place application (naturally sticky) without residue/mess
- ≡ Highly compressible to minimize contact resistance without high force and component stress



## TECHNICAL SPECIFICATIONS

Test	Description	Min	Max
Thermal Conductivity *	ASTM D5470	40 W/mK	
Thermal Impedance vs Pressure **	ASTM D5470	0.56°C-cm <sup>2</sup> /W (0.087°C-inch <sup>2</sup> /W) @10psi 0.37°C-cm <sup>2</sup> /W (0.057°C-inch <sup>2</sup> /W) @30psi	
Continuous Use Temperature	Thermexit In-House Method	-40°C	150°C
Storage Temperature/Shelf Life	Thermexit In-House Method	10-40°C for 12 months	
Total Mass Loss/TGA *	Thermal stability (TGA)	<0.2% @150°C	
Hardness *	ASTM D2240	70 Shore 00	80 Shore 00
Outgassing CVCM (Collectible Volatile Condensable Materials)	ASTM E595	0.10 Wt. %	
Outgassing TML (Total Mass Loss)	ASTM E595	0.47 Wt. %	
Compression-Deflection **	ASTM D5470/ASTM C165	50% at 45psi	
Compression Set *	ASTM D395 Method B	64% after 22hrs at RT	
Length	Major axis of the pad footprint, +/-10%	5mm	50mm
Width	Minor axis of the pad footprint, +/-10%	5mm	50mm
Thickness	Thickness of the pad, +/-10%	0.5mm	5mm
Density (Specific Gravity) *	ASTM D0792	1.73 g/mL	
Standard Color	Thermexit In-House Method	Black	
Flammability	UL94 Vertical	V1	

Standard sizes are 20mm x 20mm or 50mm x 50mm. Custom sizes available upon request.

\*Preliminary Data, \*\*1.5mm thickness: additional data available

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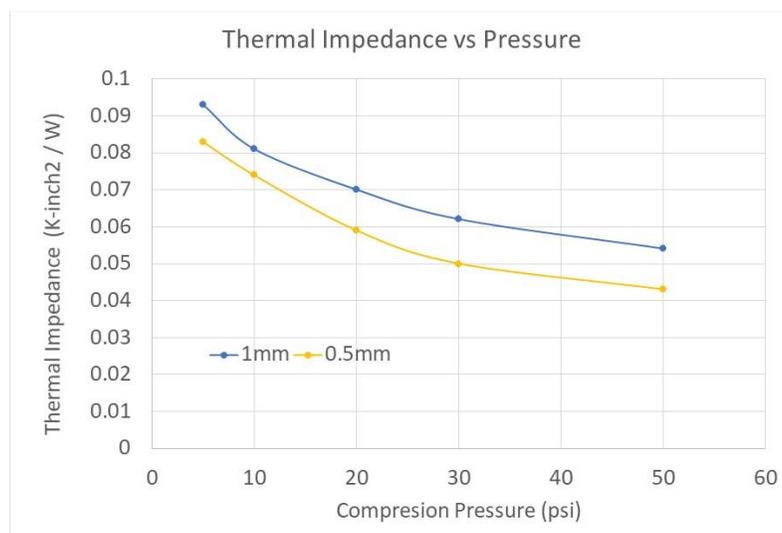
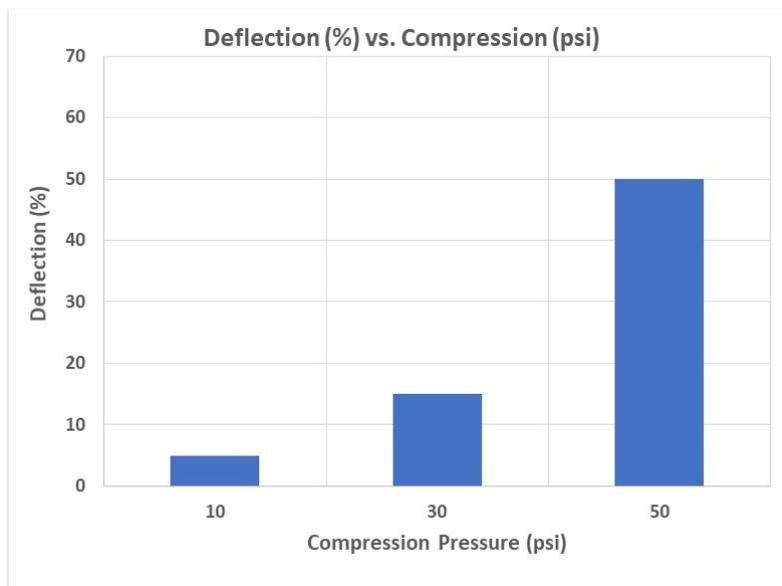
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